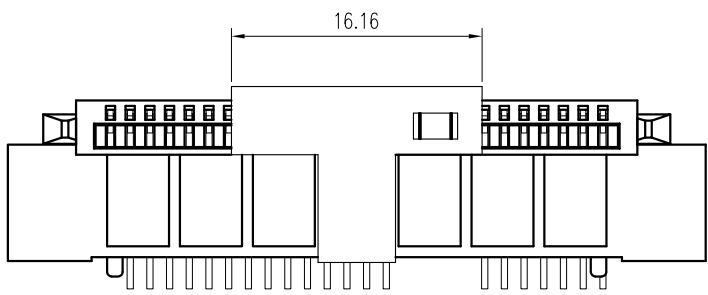
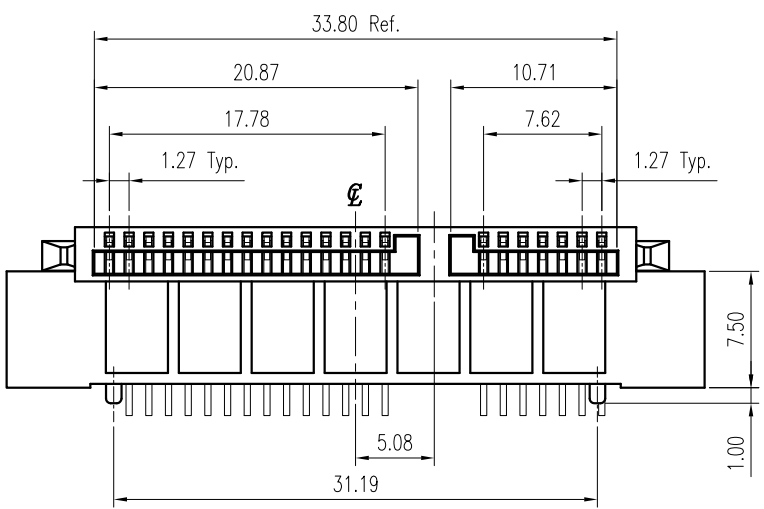
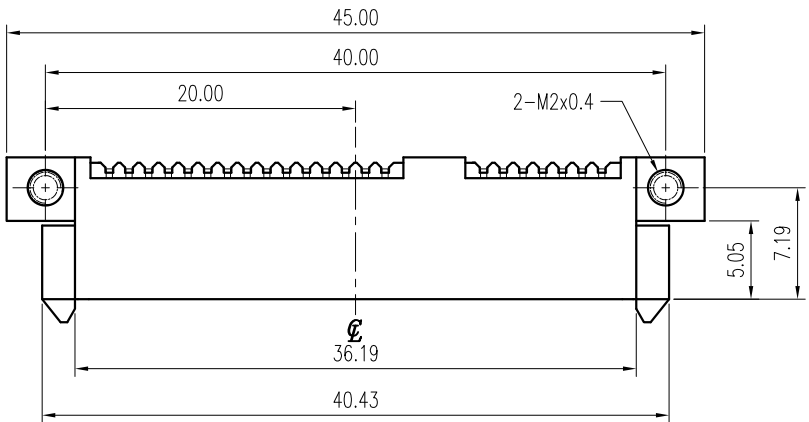
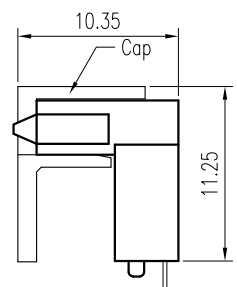
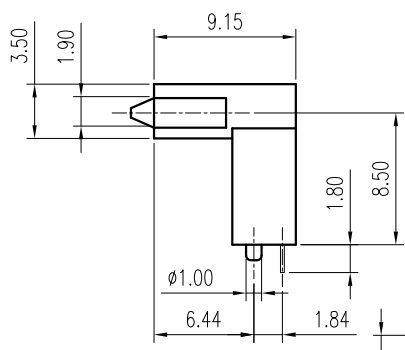


REV.	DESCRIPTION	ECN NO.	DATE	DRAWER
A	New Release		12/18/2007	Aaron



With Cap



Notes:

- Material :
Housing : Thermoplastic UL 94V-0 , Black
Terminal : Copper Alloy
Nut : Copper Alloy
- Finish :
Terminal : Selected Gold on Contact Area, 1u"
Min. Gold on Solder Tails, Both over
50u" Min. Ni Under-plated Overall
- Nut : 40u" Min. Ni Under-plated Overall
- Order Information :
T BFO-01301-21 X X

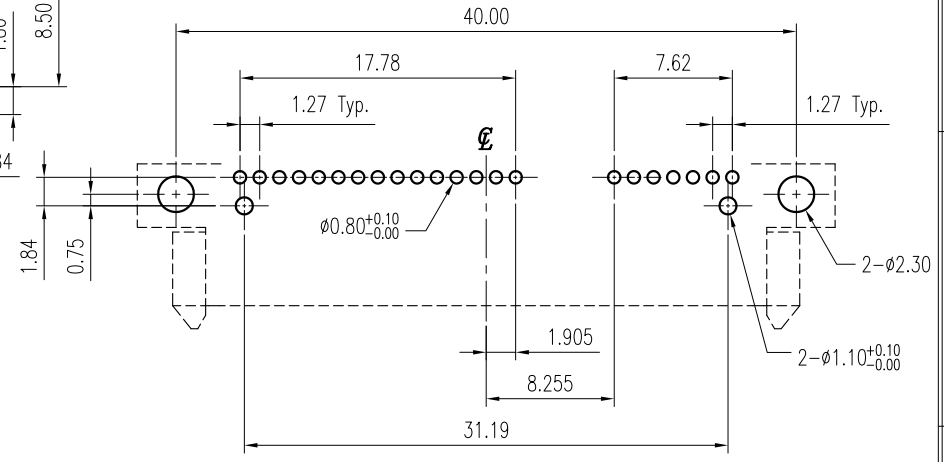
T : RoHS(for High Temperature)

Packing

- T : Tube
- 1 : Tube + Cap
- 2 : Reel + Cap

Plating

- 1 : 1u" Min. Gold on Contact Area
- 5 : 15u" Min. Gold on Contact Area



Recommended P.C.B. Layout
Layout Tolerance = ± 0.05 mm

DIMENSION IN mm [inch]		CEN 欣訊科技股份有限公司 CEN LINK CO., LTD.	Title 1.27 mm Pitch Serial ATA Conn. R/A DIP Type	Dwg No. TBFO-01301-21XX	File No. P07004	Scale: 2 : 1
Tolerance unless otherwise specified						
X.	±	X.*	± 10'	CUSTOMER DRAWING		Size: A 4
X.X	± 0.38	X.X*	± 5'	Approver:	Checker:	Rev : A
X.XX	± 0.25	X.XX*	± 2'	Drawer: Aaron		12/18/2007
X.XXX	± 0.13	X.XXX*	±			Sheet: 1 / 1